PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		MMS/16/9626
1.3 Title of PCN		Additional capacity through High Density Matrix Leadframe in ST Muar (Malaysia) - STM32F100 128K and STM8L15x 64K products in LQFP 64 10x10 package
1.4 Product Category		STM32F100 128K and STM8L15x 64K products in LQFP 64 10x10 package
1.5 Issue date		2016-02-16

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	SETTLES JEFF	
2.1.2 Phone	+44 1628896222	
2.1.3 Email	jeff.settles@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Michel BUFFA	
2.1.2 Marketing Manager	Daniel COLONNA	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site		ST Muar (Malaysia), STATS ChipPAC Shanghai (China), Amkor ATP (Philippines)

4. Description of change		
	Old	New
4.1 Description	The qualified assembly plants are ST Muar (Malaysia), STATS ChipPAC Shanghai (China) and Amkor ATP (Philippines). The Bill of Materials is described in PCN_9626_Additional information document.	To the current sources, we add an assembly line in ST Muar (Malaysia) with High Density Matrix leadframe. The Bill of Materials is described in PCN_9626_Additional information document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change		
5.1 Motivation To increase assembly capacity on an existing line, already qualified, with High Density M leadframe.		
5.2 Customer Benefit	DOUBLE SOURCING	

6. Marking of parts / traceability of change		
6.1 Description See information in PCN_9626_Additional information document.		

7. Timing / schedule		
7.1 Date of qualification results	2016-04-15	
7.2 Intended start of delivery	2016-05-15	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description PCN_9626 - MCDRER1411 Reliability plan addendum ST Muar LQFP 10x10.pdf			f
8.2 Qualification report and qualification results		Issue Date	2016-02-16

9. Attachments (additional documentations)

9626PpPrdtLst.pdf PCN_9626_Additional information.pdf PCN_9626 - MCDRER1411 Reliability plan addendum ST Muar LQFP 10x10.pdf MMS MCDRER1411 v10 Qualification Report LQFP10x10 Muar.pdf

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
	STM32F100R4T6B		
	STM32F100R8T6B		
	STM32F100RBT6B		

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